



AMP-IN

TE Internal #: 2393199-1

PCB Terminals, Receptacle, PCB Hole Diameter 1.8 – 1.9 mm [.071 – .075 in], 22 – 18 AWG Wire Size, .341 – .846 mm² Wire Size, Through Hole - Solder

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PCB Terminal Type: **Receptacle**

PCB Thickness (Recommended): **1.6 mm [.063 in]**

PCB Hole Diameter: **1.8 – 1.9 mm [.071 – .075 in]**

Profile Height from PCB: **3.5 mm [.138 in]**

Compatible Insulation Diameter (Max): **3 mm [.118 in]**

Features

Product Type Features

Terminal Features	Stud Hole
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Contact Features

Contact Underplating Material Thickness	.5 μm[19.68 μin]
Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]
PCB Terminal Type	Receptacle
Terminal Plating Material	Tin
Contact Underplating Material	Brass
Terminal Size	Miniature
Terminal Orientation	Straight

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder
Product Terminates To	Printed Circuit Board

Dimensions

Extension Below Board	2.35 mm[.093 in]
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PCB Thickness (Recommended)	1.6 mm[.063 in]
PCB Hole Diameter	1.8 – 1.9 mm[.071 – .075 in]
Profile Height from PCB	3.5 mm[.138 in]
Compatible Insulation Diameter (Max)	3 mm[.118 in]
Compatible Insulation Diameter Range	1.5 – 3. mm[.059 – .118 in]
Wire Size	.341 – .846 mm ²

Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
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Industry Standards

Agency/Standard	UL
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Packaging Features

Packaging Method	Reel
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

MINI AMP-IN BOARD IN CONTACT, 22-18AWG

English

CAD Files

Customer View Model

[ENG_CVM_CVM_2393199-1_A.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2393199-1_A.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2393199-1_A.3d_igs.zip](#)

English

3D PDF

3D

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Product Specifications

Application Specification

English